

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Kazuto NISHIDA et al.

Serial No. NEW

Filed July 26, 2001

Attn: BOX PCT

Docket No. 2001\_1055A

ELECTRONIC COMPONENT MOUNTING  
METHOD AND APPARATUS  
[Corresponding to PCT/JP00/00372  
Filed January 26, 2000]

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents,  
Washington, DC 20231

Sir:

Prior to initial examination of the above-identified New 371 National Stage application, kindly amend the application as follows:

IN THE CLAIMS:

3.(Amended) An electronic component mounting method as claimed in claim

1, wherein

the insulating resin (6m) of the anisotropic conductive layer is an insulative thermosetting epoxy resin, and an amount of the inorganic filler mixed with this insulative thermosetting epoxy resin is 5 to 90 wt% of the insulative thermosetting epoxy resin.